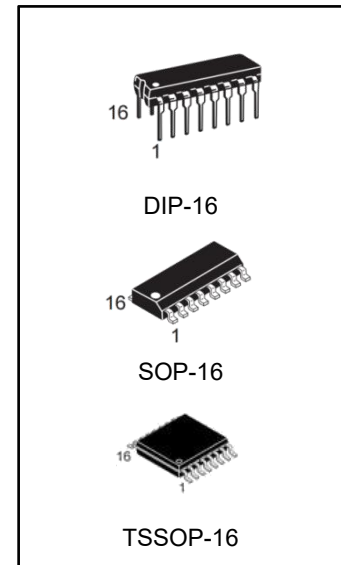


## Features

- 7-Channel High Current Sink Drivers
- Supports up to 20V Output Pull-up Voltage
- Low Output VOL of 0.6V (Typical) with
- 100mA (Typ.) Current Sink per Channel at 3.3V Logic Input
- 140mA (Typ.) Current Sink per Channel at 5.0V Logic Input
- Compatible to 3.3V and 5.0V Micro-Controllers and Logic Interface
- Internal Free-wheeling Diodes for Inductive Kick-back Protection
- Input Pull-down Resistors Allows Tri-Stating the Input Driver
- Input RC-Snubber to Eliminate Spurious Operation in Noisy Environments
- ESD: 4kV HBM, 1kV CDM
- Available in 16-Pin DIP, 16-Pin SOP and 16-Pin TSSOP packages



## Ordering Information

DEVICE	Package Type	MARKING	Packing	Packing Qty
ULN2003LVPG	DIP-16	ULN2003LV	TUBE	1000pcs/box
ULN2003LVDRG	SOP-16	ULN2003LV	REEL	2500pcs/Reel
ULN2003LVPWRG	TSSOP-16	2003LV	REEL	2500pcs/Reel

## Description

The ULN2003LV are multi-channel sink drivers comprised of 7-channel output stages. The ULN2003LV sink driver features 7 low output impedance drivers that minimize on-chip power dissipation and an actual low power upgrade version for popular ULN2003A family in real applications. When driving a typical 12V relay coil, a ULN2003LV will dissipate 12 times lower power compared to ULN2003A.

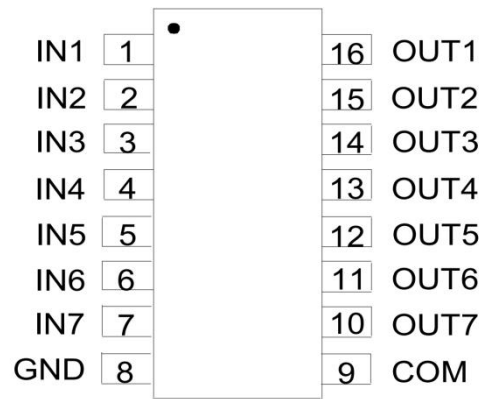
The ULN2003LV both support 3.3V to 5V CMOS logic input interface, thus making it compatible to a wide range of micro-controllers and other logic interfaces, and also feature an improved input interface that minimizes the input DC current drawn from the external drivers. The input RC snubber circuit integrated at ULN2003LV improves the performance in noisy operating conditions, and the internal pull-down resistor at input stage helps allow input logic to be tri-stated.

As shown in the Functional Diagram, each output of the ULN2003LV features an internal free-wheeling diode connected in a common-cathode configuration at the COM pin which provides flexibility of increasing current sink capability through combining several adjacent channels in parallel. Under typical conditions the ULN2003LV can support up to 1.0A of load current when all 7- channels are connected in parallel.

## Applications

- Inputs Compatible with Popular Logic Types
- Relay Driver Applications
- Stepping Motor Applications
- Logic Level Shifter

## Pin Assignments

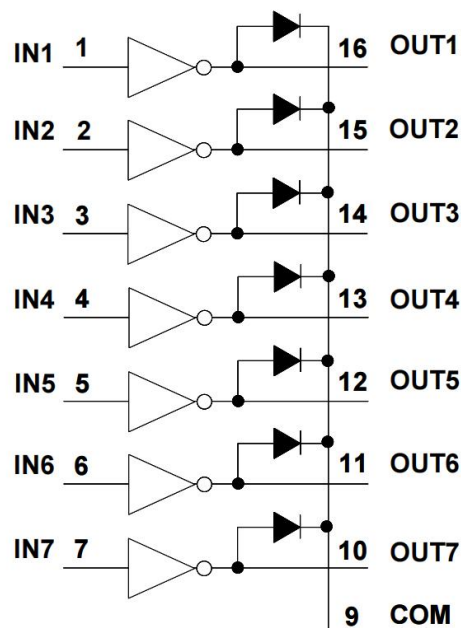


DIP-16/SOP-16/TSSOP-16  
(Top View)

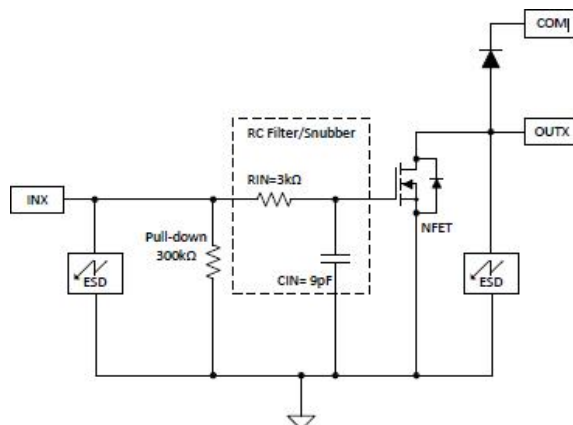
## Pin Descriptions

Pin Name	Pin Number	Description
IN1 ~ IN7	1~7	Logic Input Pins IN1 through IN7
GND	8	Ground Reference Pin
COM	9	Internal Free-Wheeling Diode Common Cathode Pin
OUT7 ~ OUT1	10~16	Channel Output Pins OUT7 through OUT1

## Functional Diagram



ULN2003LV

**Functional Block Diagram (Single Channel)**

**Absolute Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Symbol	Parameter	Rating		Unit	
		MIN	MAX		
$V_{IN}$	Pin2 IN1~IN7 to GND Voltage	-0.3	5.5	V	
$V_{OUT}$	Pins OUT1~OUT7 to GND Voltage	-	20	V	
$V_{COM}$	Pin COM to GND Voltage	-	20	V	
$I_{GND}$	Max GND-Pin Continuous Current ( $+100^\circ\text{C} < T_J < +125^\circ\text{C}$ )	-	700	mA	
	Max GND-Pin Continuous Current ( $T_J < +100^\circ\text{C}$ )	-	1.0	A	
$P_D$	Total Device Power Dissipation at $T_A = +85^\circ\text{C}$	16 Pin – SOP	TBD		W
		16 Pin – TSSOP	TBD		W
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient (Note 6)	16 Pin – SOP	TBD		$^\circ\text{C/W}$
		16 Pin – TSSOP	TBD		
$\theta_{JC}$	Thermal Resistance Junction-to-Case (Note 7)	16 Pin – SOP	TBD		$^\circ\text{C/W}$
		16 Pin – TSSOP	TBD		
ESD	HBM	-	4	kV	
	CDM	-	1	kV	
$T_J$	Junction Temperature	-55	150	$^\circ\text{C}$	
$T_{STG}$	Storage Temperature	-55	150	$^\circ\text{C}$	
$T_L$	Lead Temperature (Soldering, 10 seconds)	-	245	$^\circ\text{C}$	

Notes:

- Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only.  
Functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.  
Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- All voltage values are with respect to the emitter/substrate terminal E, unless otherwise noted.
- Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of  $+150^\circ\text{C}$  can affect reliability.
- Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JC}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_C)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of  $+150^\circ\text{C}$  can affect reliability.

**Recommended Operating Conditions** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	TYP	Max	Unit	
V <sub>OUT</sub>	Channel Off-Stage Output Pull-Up Voltage	-	-	16	V	
V <sub>COM</sub>	COM Pin Voltage	-	-	16	V	
I <sub>OUT(ON)</sub>	Per Channel Continuous Sink Current	V <sub>INX</sub> = 3.3V	-	-	100 <sup>(5)</sup>	mA
		V <sub>INX</sub> = 5.0V	-	-	140 <sup>(5)</sup>	
T <sub>J</sub>	Operating Junction Temperature	-40	-	125	°C	

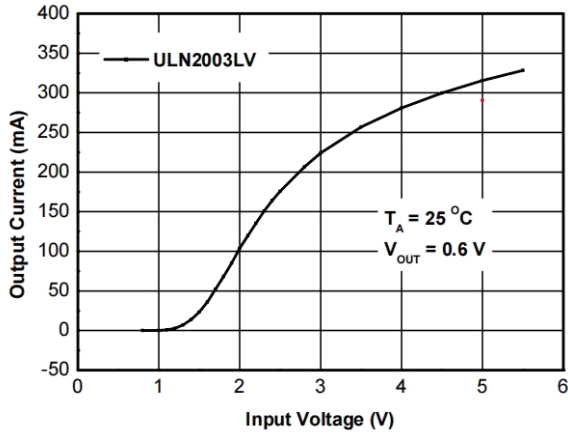
**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Specified over the recommended junction temperature range T<sub>J</sub>=-40°C to +125°C and over recommended operating conditions unless otherwise noted. Typical values are at T<sub>J</sub> = +25°C.

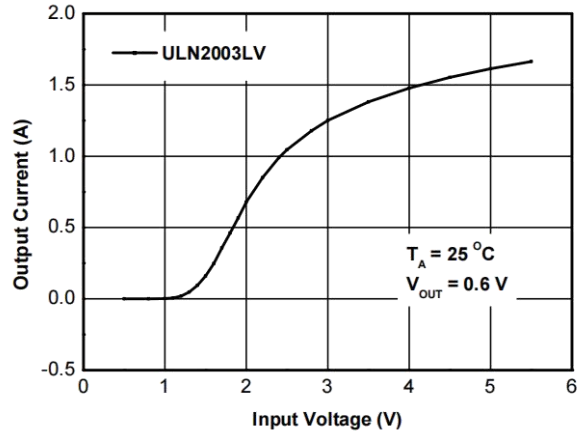
Parameter	Test conditions	Min	Typ.	Max	Unit		
<b>INPUTS IN1 THROUGH IN7 PARAMETERS</b>							
V <sub>I(ON)</sub>	IN1~IN7 logic high input voltage	V <sub>CE</sub> = 2V, I <sub>C</sub> = 80mA		1.65	-	-	V
V <sub>I(OFF)</sub>	IN1~IN7 logic low input voltage	I <sub>C</sub> = 5μA		-	-	0.5	V
I <sub>I(ON)</sub>	IN1~IN7 ON state input current	V <sub>i</sub> =3.3V		-	12	25	μA
I <sub>I(OFF)</sub>	IN1~IN7 OFF state input leakage	V <sub>i</sub> =0V		-	-	250	nA
<b>OUTPUTS OUT1 THROUGH OUT7 PARAMETERS</b>							
V <sub>OL(VCE-SAT)</sub>	OUT1~OUT7 low-level output voltage	V <sub>INX</sub> = 3.3V, I <sub>OUTX</sub> = 20mA		-	0.12	0.15	V
		V <sub>INX</sub> = 3.3V, I <sub>OUTX</sub> = 100mA		-	0.6	0.75	
		V <sub>INX</sub> = 5.0V, I <sub>OUTX</sub> = 20mA		-	0.09	0.11	
		V <sub>INX</sub> = 5.0V, I <sub>OUTX</sub> = 140mA		-	0.6	0.75	
I <sub>OUT(ON)</sub>	OUT1~OUT7 ON-state continuous current at V <sub>OUTX</sub> = 0.6V	V <sub>INX</sub> = 3.3V, V <sub>OUTX</sub> = 0.6V		80	100	-	mA
		V <sub>INX</sub> = 5.0V, V <sub>OUTX</sub> = 0.6V		95	140	-	
I <sub>OUT(ON)</sub>	OUT1~OUT7 OFF-state leakage current	V <sub>INX</sub> = 0V, V <sub>OUTX</sub> = V <sub>COM</sub> = 16V		-	0.5	-	μA
<b>SWITCHING PARAMETERS</b>							
t <sub>PHL</sub>	OUT1~OUT7 logic high propagation delay	V <sub>INX</sub> = 3.3V, V <sub>pull-up</sub> = 12V, R <sub>pull-up</sub> = 1kΩ		-	50	70	ns
t <sub>PLH</sub>	OUT1~OUT7 logic low propagation delay	V <sub>INX</sub> = 3.3V, V <sub>pull-up</sub> = 12V, R <sub>pull-up</sub> = 1kΩ		-	121	140	ns
t <sub>CHANNEL</sub>	Channel to channel delay	Over recommended operating conditions and with same test conditions on channels.		-	15	50	ns
R <sub>PD</sub>	IN1~IN7 input pull-down resistance	-		210k	300k	390k	Ω
ζ	IN1~IN7 input filter time constant	-		-	9	-	ns
C <sub>OUT</sub>	OUT1~OUT7 output capacitance	V <sub>INX</sub> = 3.3V, V <sub>OUTX</sub> = 0.4V		-	15	-	pF
<b>FREE-WHEELING DIODE PARAMETERS</b>							
V <sub>F</sub>	Forward voltage drop	I <sub>F-peak</sub> = 140mA, V <sub>F</sub> = V <sub>OUTX</sub> - V <sub>COM</sub>		-	1.2	-	V
I <sub>F-peak</sub>	Diode peak forward current	-		-	140	-	mA

**Performance Characteristics**

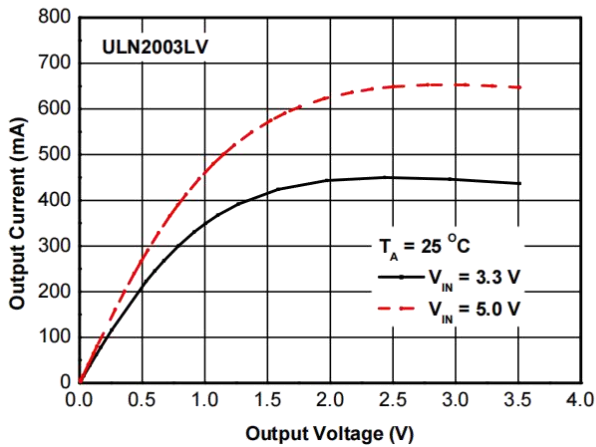
Output Current vs. Input Voltage (One Darlington)



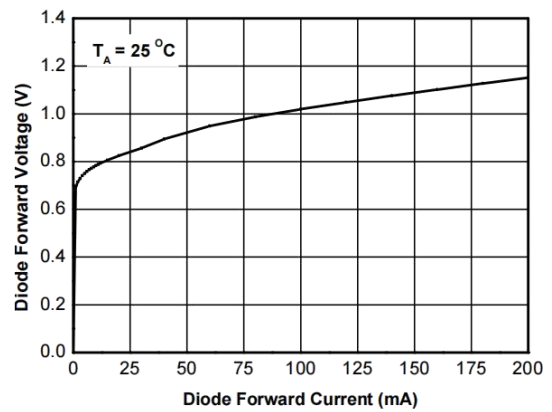
Output Current vs. Input Voltage (All Darlings in Parallel)



Output Current vs. Output Voltage

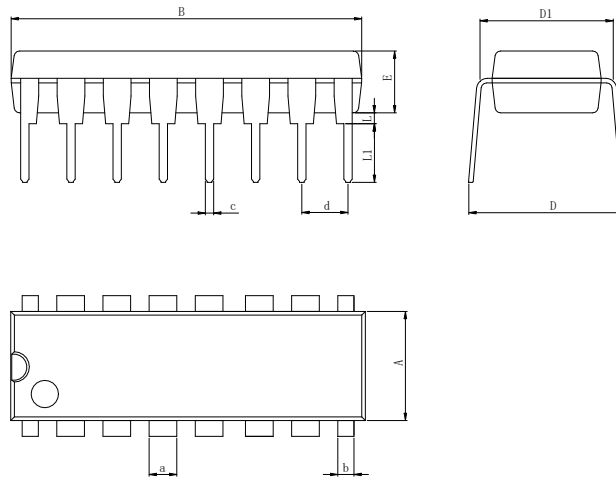


Diode Forward Voltage vs. Diode Forward Current



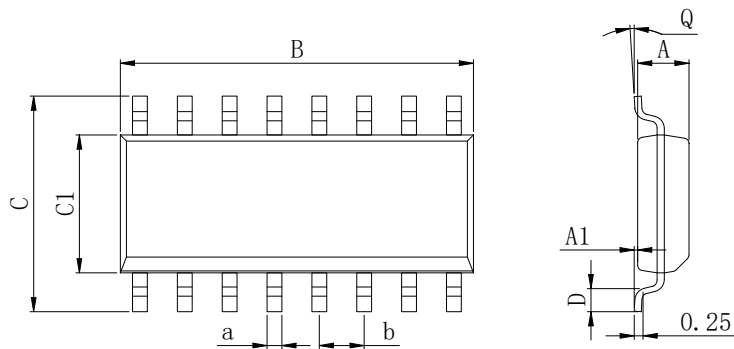
### Physical Dimensions

#### DIP-16



Dimensions In Millimeters(DIP-16)											
Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	18.94	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	19.56	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

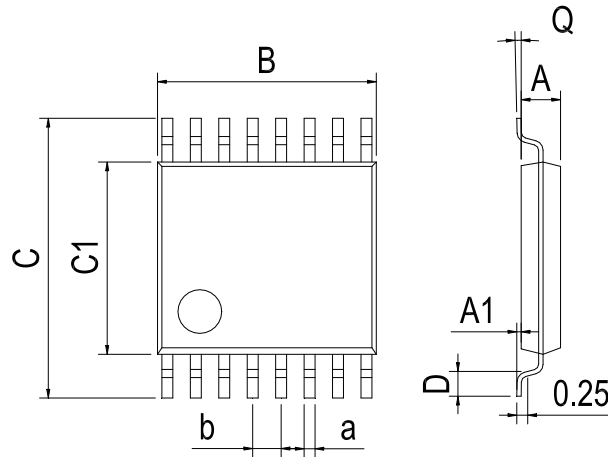
#### SOP-16



Dimensions In Millimeters(SOP-16)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	9.80	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	10.0	6.20	4.00	0.80	8°	0.45	

**Physical Dimensions**

TSSOP-16


**Dimensions In Millimeters(TSSOP-16)**

Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.85	0.05	4.90	6.20	4.30	0.40	0°	0.20	0.65 BSC
Max:	0.95	0.20	5.10	6.60	4.50	0.80	8°	0.25	



## Revision History

DATE	REVISION	PAGE
2020-10-5	New	1-10
2023-8-26	Modify the package dimension diagram TSSOP-16、 Update encapsulation type、 Update Lead Temperature、 Updated DIP-16 dimension	1、 4、 7、 10

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